

L Number	Hits	Search Text	DB	Time stamp
1	2	("5889326").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:16
2	9	("4724472"   "4970570"   "5028987"   "5422516"   "5508561"   "5611481"   "5640051"   "5640052"   "5641113").PN.	USPAT	2004/09/10 09:11
3	27	5889326.URPN.	USPAT	2004/09/10 09:12
4	3540	((257/747) or (257/759) or (257/773) or (257/779)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:17
5	5624	organic adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:17
6	60	((257/747) or (257/759) or (257/773) or (257/779)).CCLS.) and (organic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:28
7	113	(257/474).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:29
8	256	(257/747).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:29
-	7	semiconductor adj substrate and organic adj substrate and pad and solder and ("coefficent of thermal expansion" or cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 09:08
-	6	("5471090"   "6005292"   "6046910"   "6118181"   "6232668"   "6271597").PN.	USPAT	2002/11/05 12:59
-	0	6310403.URPN.	USPAT	2002/11/05 13:02
-	6	("5471090"   "6005292"   "6046910"   "6118181"   "6232668"   "6271597").PN.	USPAT	2002/11/05 13:02
-	9	("3842189"   "4056681"   "4647959"   "4949148"   "5214308"   "5302854"   "5331513"   "5528461"   "5657207").PN.	USPAT	2002/11/05 13:02
-	5	6046910.URPN.	USPAT	2002/11/05 13:03
-	4345	"coefficent of thermal expansion" or cte	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:16
-	31	((257/786).CCLS.) and ("coefficent of thermal expansion" or cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:06
-	1299	c4 same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 13:07

-	169	("coefficent of thermal expansion" or cte) and (c4 same solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/06 13:55
-	327	gigapascal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/05 13:16
-	19	("coefficent of thermal expansion" or cte) and gigapascal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/05 13:18
-	0	underfill adj material same gigapascal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/05 13:19
-	775	underfill adj material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/05 13:19
-	188	("coefficent of thermal expansion" or cte) and (underfill adj material )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/05 13:19
-	143	conductive adj pad and solder and bump and c4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/05 13:41
-	1235	(257/786).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/06 09:10
-	195	c4 and solder and ("coefficent of thermal expansion" or cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/06 13:51
-	7841	(lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/06 14:46
-	20	("coefficent of thermal expansion" or cte) and (c4 same solder) and ((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/06 13:56
-	2570	(lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn) and c4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/06 15:00
-	14566	flip adj chip or flipchip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/06 14:47
-	386	((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn) and c4) and (flip adj chip or flipchip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/06 14:47

-	245	((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn)) and c4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 15:01
-	69	larger near pad and smaller near pad and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/11 10:14
-	6	("4673772"   "5616520"   "5761048"   "5859407"   "5907187"   "6093964").PN.	USPAT	2003/11/11 10:23
-	1	6285083.URPN.	USPAT	2003/11/11 10:25
-	2	6274474.URPN.	USPAT	2003/11/11 10:32
-	0	beriner.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:41
-	670	bernier.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:41
-	7	solder adj ball and bernier.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:43
-	6925	carey.in. or gramatzki.in. or homa.in. or langevin.in. or tran.in. or white.in	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:44
-	20	solder adj ball and (carey.in. or gramatzki.in. or homa.in. or langevin.in. or tran.in. or white.in)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/18 13:45
-	57	5075965.URPN.	USPAT	2003/11/18 13:50
-	0	6330967.URPN.	USPAT	2003/11/18 13:54
-	25	("4545610"   "5060844"   "5075965"   "5161729"   "5221038"   "5234152"   "5372298"   "5429292"   "5470787"   "5473814"   "5580668"   "5591941"   "5634268"   "5639696"   "5675889"   "5729896"   "5796591"   "5808853"   "5825629"   "5912505"   "5953623"   "5965945"   "6121069"   "6130476"   "6162660").PN.	USPAT	2003/11/18 13:54
-	27	organic adj substrate and (bump or electrode or pad) and solder adj ball and semiconductor adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/03 14:30